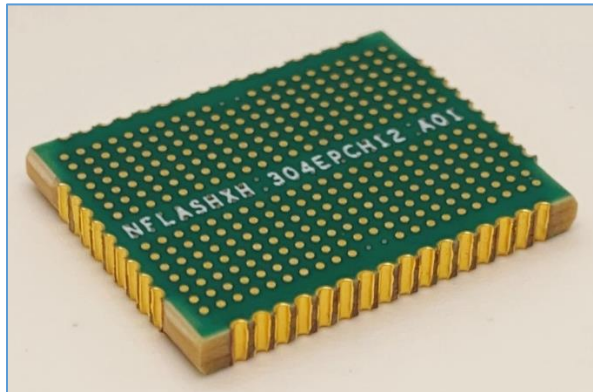


# NAND Interposers

NAND 304 Ball EdgeProbe



## Key Features

- NAND Flash
- XH Series Universal Probe Interposer
- 304-Ball
- EdgeProbe™ Interposer
- High Fidelity
- Enables Oscilloscope Probing
- Patented Interposer/Probe Design

## Applications

- NAND Flash
  - Memory validation and debug
  - Monitoring bus traffic
  - Bus traffic measurement
  - Analog insight

## EdgeProbe™ Interposer Technology



Nexus Technology's patented EdgeProbe™ technology enables our interposers to be virtually the same size as the memory component. This is important

because standard direct-attach interposers are significantly larger than the memory component which can potentially cause mechanical clearance problems. In other words, standard direct-attach interposers do not fit in all applications. EdgeProbe™ interposers fit in all applications.

EdgeProbe™ interposers provide advanced analysis capabilities by integrating the oscilloscope probe into the interposer. In doing so, the probe point moves extremely close to the component pad which is the optimal and least intrusive location.

## Simulation and De-Embedding

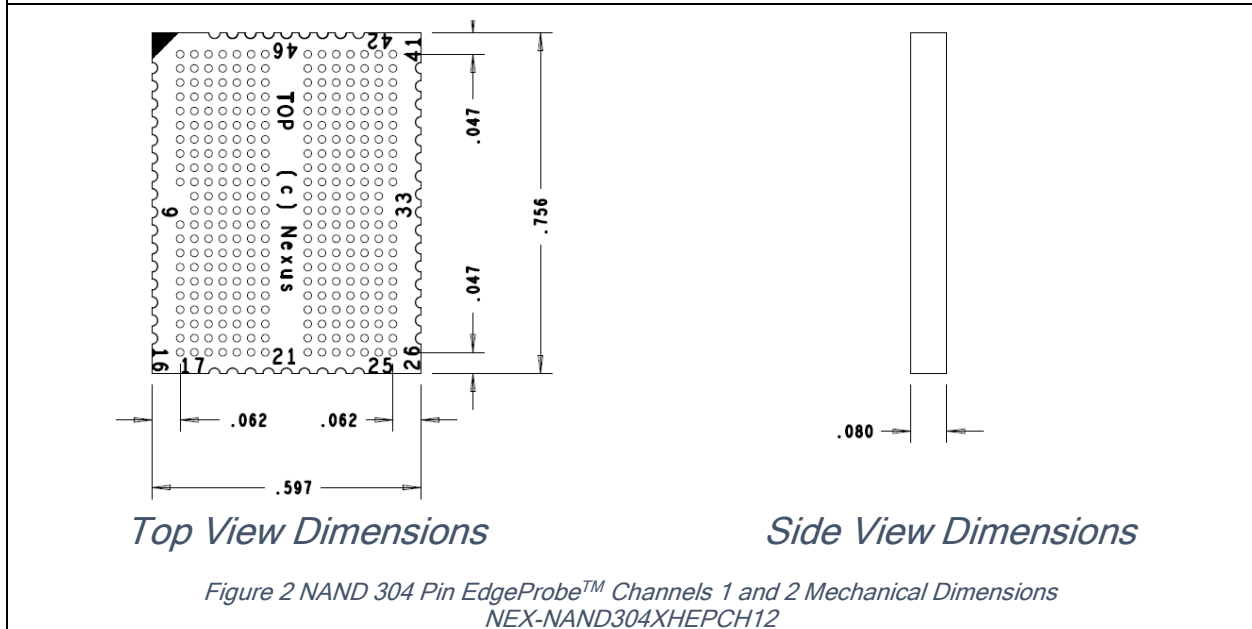
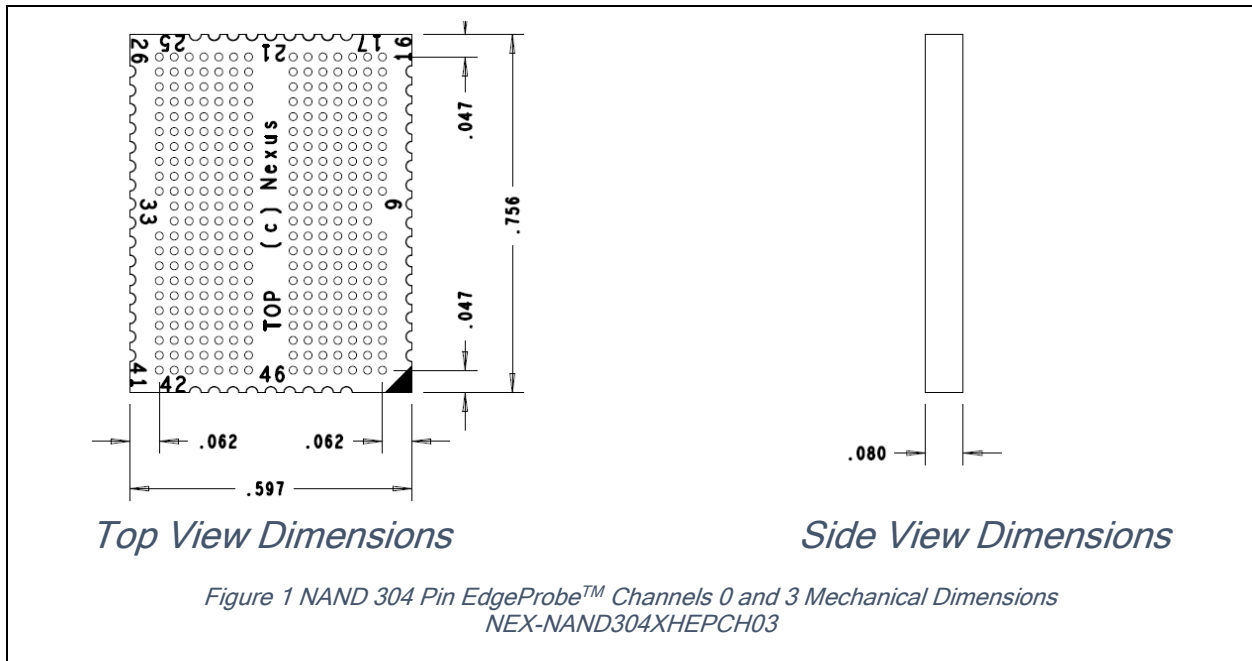
S-Parameters are included for target simulation and the creation of de-embedding filters for use with an oscilloscope.

## Attachment Service

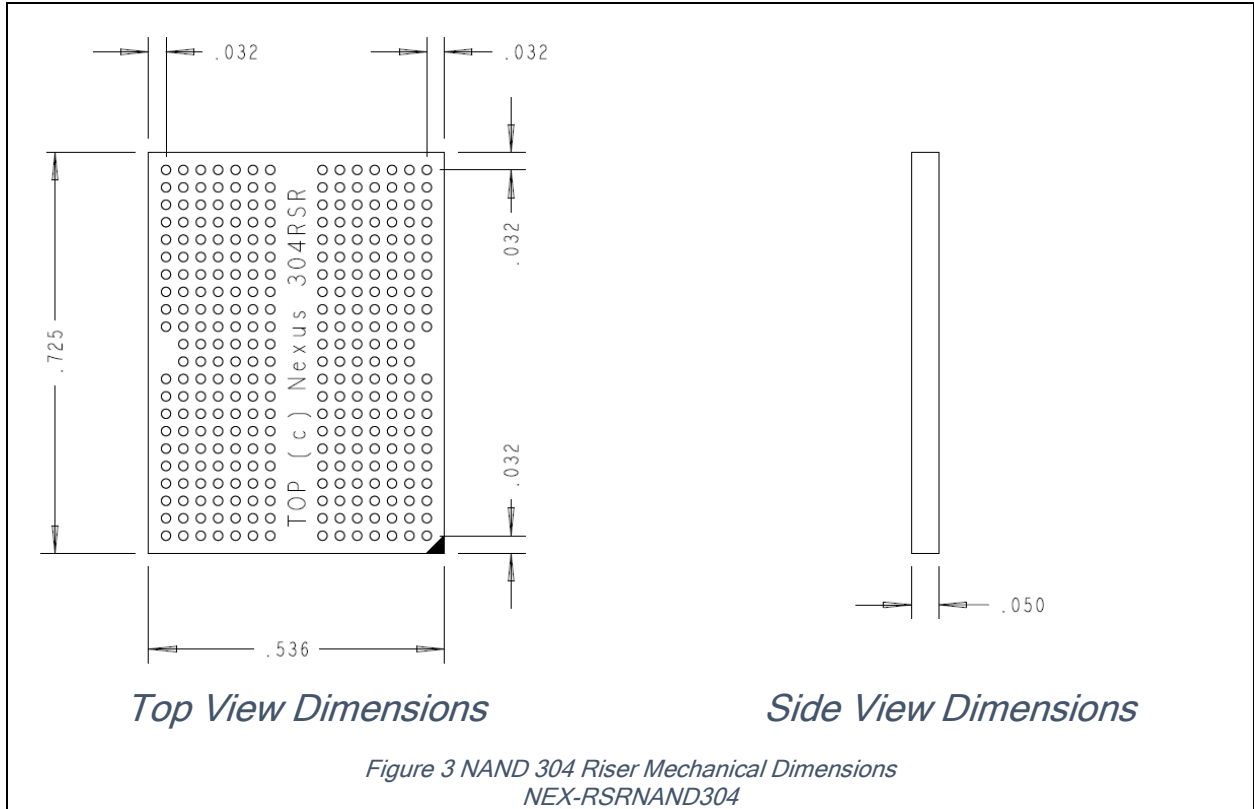
Nexus Technology's expert attachment service provides a ready-to-go test solution customized to your application. We will attach the interposer and any additional accessories to your application's target. We can also power-on and test your application to confirm functionality. Please contact us for more information.



## Mechanical Outline



Note: All measurements listed are in inches.



## Probe Point Signal List

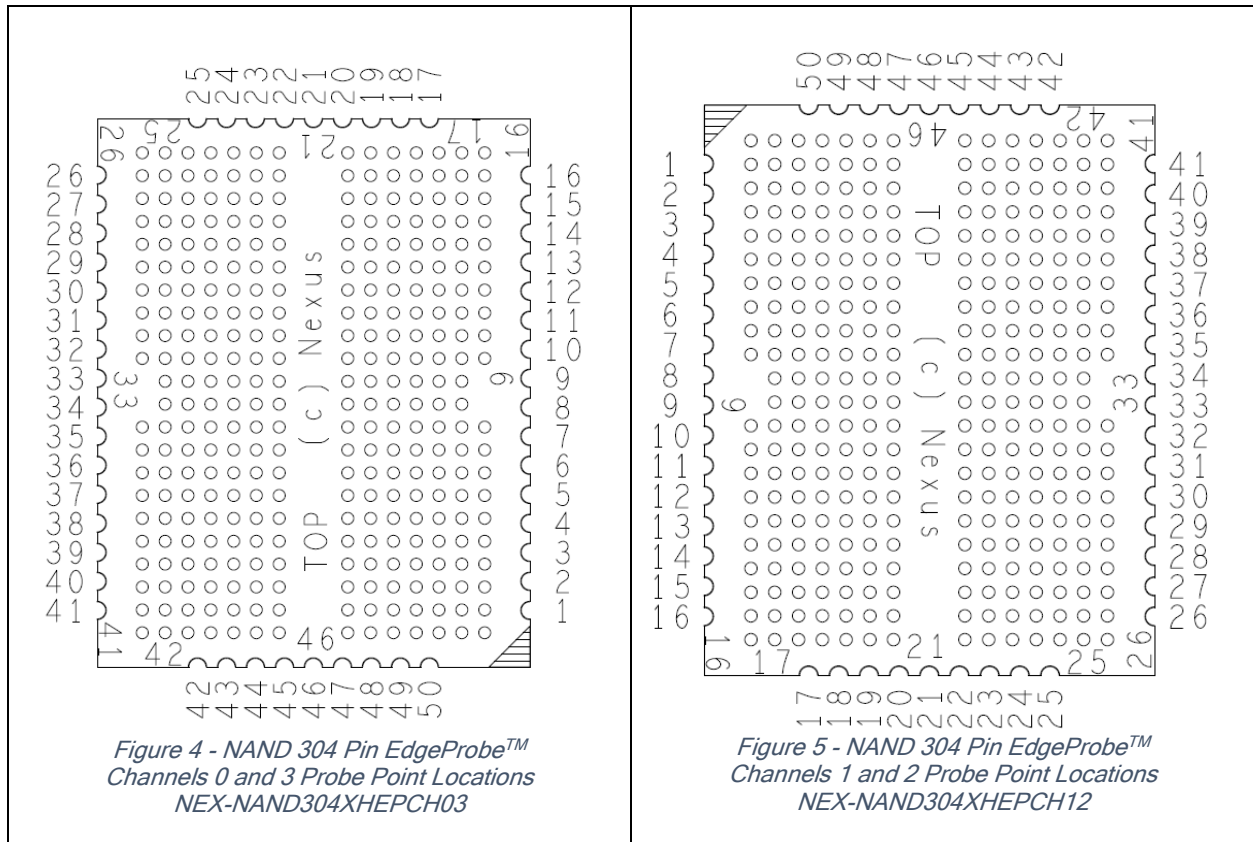
### NEX-NAND304XHEPCH03 NAND 304 Ball EdgeProbe™ Channels 0 and 3

TEST Point	Signal	TEST Point	Signal	TEST Point	Signal
1	GROUND	18	NU/DQ2_3	35	NU/ALE_3
2	DQ3_0	19	NU/DQ1_3	36	GROUND
3	DQS_0	20	NU/DQ0_3	37	CE0_0
4	DQS_0c	21	GROUND	38	WE_0
5	WP_0	22	NU/DQ4_3	39	RB0_0
6	GROUND	23	NU/DQ5_3	40	DQ7_0
7	RE_0n	24	NU/DQ6_3	41	GROUND
8	ALE_0	25	GROUND	42	GROUND
9	RE_0c	26	GROUND	43	DQ2_0
10	CLE_0	27	NU/DQ3_3	44	DQ1_0
11	GROUND	28	NU/DQS_3	45	DQ0_0
12	CE0_3	29	NU/DQS_3c	46	GROUND
13	NU/WE_3	30	NU/RE_3n	47	DQ4_0
14	NU/DQ7_3	31	GROUND	48	DQ5_0
15	RB0_3	32	NU/RE_3c	49	DQ6_0
16	GROUND	33	NU/WP_3	50	GROUND
17	GROUND	34	NU/CLE_3		

### NEX-NAND304XHEPCH12 NAND 304 Ball EdgeProbe™ Channels 1 and 2

TEST Point	Signal	TEST Point	Signal	TEST Point	Signal
1	GROUND	18	DQ2_1	35	CLE_1
2	NC/DQ3_2	19	DQ1_1	36	GROUND
3	NC/DQS_2	20	DQ0_1	37	CE0_2
4	NC/DQS_2c	21	GROUND	38	NU/WE_2
5	NC/RE_2n	22	DQ4_1	39	NU/DQ7_2
6	GROUND	23	DQ5_1	40	RB0_2
7	NC/RE_2c	24	DQ6_1	41	GROUND
8	NC/WP_2	25	GROUND	42	GROUND
9	NC/CLE_2	26	GROUND	43	NC/DQ2_2
10	NC/ALE_2	27	DQ3_1	44	NC/DQ1_2
11	GROUND	28	DQS_1	45	NC/DQ0_2
12	CE0_1	29	DQS_1c	46	GROUND
13	WE_1	30	WP_1	47	NU/DQ4_2
14	RB0_1	31	GROUND	48	NU/DQ5_2
15	DQ7_1	32	RE_1n	49	NU/DQ6_2
16	GROUND	33	ALE_1	50	GROUND
17	GROUND	34	RE_1c		

## Probe Point Locations



### Product Configuration Table

Nomenclature	Riser Included	Channels Probed
NEX-NAND304XHEP03	No	Channel 0 and 3
NEX-NAND304XHEP12	No	Channel 1 and 2

### Available Accessories

Type	Desc.	Quantity	Nomenclature
Riser	Riser with Solder balls added elevates interposer 0.50"	1	NEX-RSRNAND304
Solder Balls	Install solder balls in EdgeProbe Interposer	1	NEX-OPT-SOLDERBALLS-EP

### Attachment Service Options

Attachment Service Level	Description
Attachment Service	Contact us for more information

### Contact Information

For more information, please contact us by telephone, email or mail as listed below. Normal business hours are 9:00 - 5:00 EDT/EST.

Web	<a href="http://www.nexustechnology.com">www.nexustechnology.com</a>
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Address	78 Northeastern Blvd. Unit 2 Nashua, NH 03062
Email	<a href="mailto:support@nexustechnology.com">support@nexustechnology.com</a>